

Part Number: **BAVxxxT-(p)-F (Date Code 0740+)**
Weight (mg): 2.61

p = package designator
See Data Sheet

p= 7, 13

xxx= 170, 199, 70, 99

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	100.00%	6.63	0.17	1000000	66253
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	38.23	1.00	576500	220388
		Ni	7440-02-0	41.00%			410000	156737
		Mn	7439-96-5	0.60%			6000	2294
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	382
		Co	7440-48-4	0.50%			5000	1911
		Si	7440-21-3	0.15%			1500	573
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.14	0.03	1000000	11444
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.85	0.02	1000000	8459
Encapsulation	CEL-1702HF-9	SiO2	60676-86-0	87.30%	51.68	1.35	873000	451152
		Epoxy Resin	29690-82-2	5.00%			50000	25839
		Phenol Resin	26834-02-6	5.00%			50000	25839
		Misc.	system	2.50%			25000	12920
		Carbon black	1333-86-4	20.00%			200000	103357
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.48	0.04	1000000	14774
Total					100.00	2.61		1102323

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)